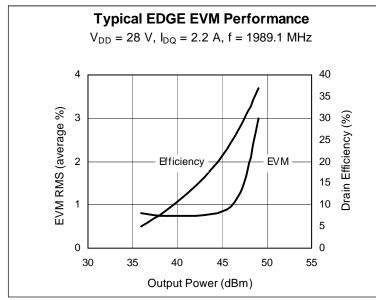


Advance Information PTF191601

LDMOS RF Power Field Effect Transistor 160 W, 1930 – 1990 MHz

Description

The PTF191601 is a 160 W, internally matched *GOLDMOS* FET intended for GSM and EDGE applications in the 1930 to 1990 MHz band. Full gold metallization ensures excellent device lifetime and reliability.



Features

- Broadband internal matching
- Typical EDGE performance
 - Average output power = 62 W
 - Gain = 14 dB
 - Efficiency = 32%
 - EVM = 1.7%
- Typical CW performance
 Output power at P–1dB = 180 W
 - Gain = 13 dB
 - Efficiency = 47%
- Integrated ESD protection: Human Body Model, Class 1 (minimum)
- Excellent thermal stability
- Low HCI drift
- Capable of handling 10:1 VSWR @ 28 V, 160 W (CW) output power



ESD: Electrostatic discharge sensitive device—observe handling precautions!

RF Characteristics at T_{CASE} = 25°C unless otherwise indicated

EDGE Measurements (not subject to production test—verified by design/characterization in Infineon test fixture) V_{DD} = 28 V, I_{DQ} = 2.2 A, P_{OUT} = 62 W, f = 1989.8 MHz

Characteristic	Symbol	Min	Тур	Max	Units
Error Vector Magnitude	EVM (RMS)	_	1.7	_	%
Modulation Spectrum @ 400 kHz	ACPR	_	-60		dBc
Modulation Spectrum @ 600 kHz	ACPR	_	-73		dBc
Gain	G _{ps}	_	14	_	dB
Drain Efficiency	η	_	32		%

Two-Tone Measurements (tested in Infineon test fixture)

 V_{DD} = 28 V, I_{DQ} = 2.2 A, P_{OUT} = 160 W PEP, f = 1990 MHz, tone spacing = 1 MHz

Characteristic	Symbol	Min	Тур	Max	Units
Gain	G _{ps}	_	14	_	dB
Drain Efficiency	η_D	—	36	—	%
Intermodulation Distortion	IMD	—	-30	—	dBc



DC Characteristics at $T_{CASE} = 25^{\circ}C$ unless otherwise indicated

Characteristic	Conditions	Symbol	Min	Тур	Max	Units	
Drain-Source Breakdown Voltage	V_{GS} = 0 V, I_{DS} = 10 μ A	V _{(BR)DSS}	65	_	_	V	
Drain Leakage Current	$V_{DS} = 28 \text{ V}, V_{GS} = 0 \text{ V}$	I _{DSS}	_	_	1.0	μA	
On-State Resistance	$V_{GS} = 10 \text{ V}, V_{DS} = 0.1 \text{ V}$	R _{DS(on)}	_	0.07	_	Ω	
Operating Gate Voltage	$V_{DS} = 28 \text{ V}, I_{DQ} = 2.2 \text{ A}$	V _{GS}	2.5	3.2	4.0	V	
Gate Leakage Current	$V_{GS} = 10 \text{ V}, V_{DS} = 0 \text{ V}$	I _{GSS}	_	_	1.0	μA	

Maximum Ratings

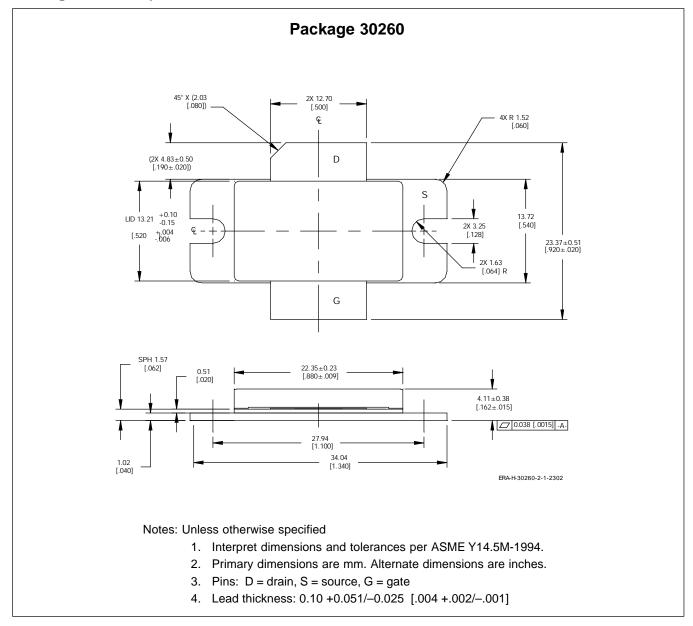
Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	65	V
Gate–Source Voltage	V _{GS}	-0.5 to +12	V
Operating Junction Temperature	ТJ	200	°C
Total Device Dissipation	PD	583	W
Above 25°C derate by		3.33	W/°C
Storage Temperature Range	T _{STG}	-40 to +150	°C
Thermal Resistance (T _{CASE} = 70°C, 130 W CW)	$R_{ extsf{ heta}JC}$	0.30	°C/W



Ordering Information

Туре	Package Outline	Package Description	Marking
PTF191601E	30260	Thermally enhanced, flange mount	PTF191601E

Package Outline Specifications



Find the latest and most complete information about products and packaging at the Infineon Internet page http://www.infineon.com/products

PTF191601 Limited Dis Revision H	stribution	Developmental Data Sheet
Previous Ve	ersion: none	
Page	Subjects (major changes since last revision)	

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